

What is claimed is:

1 1. An electronic parts mount method for taking out
2 electronic parts in wafer shape and transporting and
3 mounting the electronic parts to and on a board by a
4 transfer head including a plurality of suction nozzles, the
5 method comprising the steps of:

6 image picking up for picking up an image of the
7 electronic parts in wafer shape by advancing an image
8 pickup means to above a wafer hold section for holding the
9 electronic parts, wherein the image pick up means is
10 disposed in a manner that the image pick up means can
11 advance to and retreat from the wafer hold section;

12 position detecting for detecting positions of the
13 electronic parts based on image data obtained by the step
14 of image picking up;

15 parts taking out for controlling the head move means
16 based on a result of the step of position detecting, and
17 taking out the electronic parts in order from the wafer
18 hold section by the transfer head; and

19 parts mounting for moving the transfer head to above
20 the board positioned by a board positioning section, and
21 mounting the electronic parts on the board;

22 wherein the steps of parts mounting and image picking
23 up for the electronic parts to be next taken out are
24 performed concurrently.

1 2. The electronic parts mount method according to Claim
2 1,

3 wherein, in the step of image picking up, the image
4 pickup means picks up an image of a plurality of electronic
5 parts when the image pick up means is advanced to above the
6 wafer hold section.

1 3. The electronic parts mount method according to Claim
2 2,

3 wherein, the plurality of electronic parts whose image
4 is picked up by the image pickup means are electronic parts
5 to be next taken out by the transfer head.

1 4. The electronic parts mount method according to Claim
2 1,

3 wherein, in the step of image picking up, the image
4 pickup means retreats to the front side of the side of a
5 wafer stock section placed adjacent to the wafer hold
6 section after picking up the image of the electronic parts,
7 and the transfer head is moved to above the wafer hold
8 section.